

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
150V	5.8mΩ@10V	170A

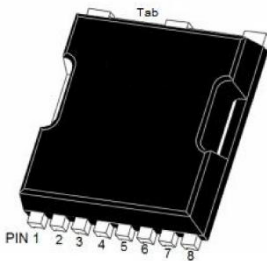
Feature

- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$

Application

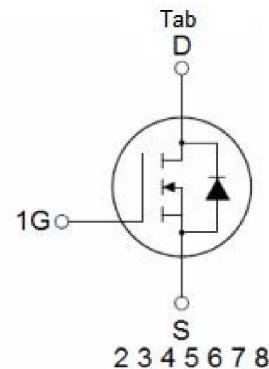
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

Package

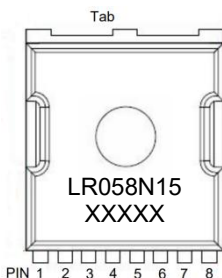


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Circuit diagram



Marking



Absolute maximum ratings (Tc=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	150	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _D	170	A
Continuous Drain Current (T _c =100°C)	I _D	120	A
Pulsed Drain Current ¹⁾	I _{DM}	680	A
Power Dissipation	P _D	380	W
Thermal Resistance,Junction-to-Case ²⁾	R _{θJC}	0.4	°C/W
Single pulse avalanche energy ⁵⁾	E _{AS}	1300	mJ
Junction Temperature	T _J	175	°C
Storage Temperature	T _{STG}	-55 ~ +175	°C

Electrical characteristics (Tc=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250μA	150			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =150V, V _{GS} = 0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} =±20V, V _{DS} = 0V			±100	nA
Gate threshold voltage ³⁾	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.0	3.0	4.0	V
Drain-source on-resistance ³⁾	R _{DS(on)}	V _{GS} =10V, I _D =85A		5.0	5.8	mΩ
Dynamic characteristics⁴⁾						
Input Capacitance	C _{iss}	V _{DS} =75V, V _{GS} =0V, f =1MHz		5500		pF
Output Capacitance	C _{oss}			690		
Reverse Transfer Capacitance	C _{rss}			24		
Total Gate Charge	Q _g	V _{DS} =75V, V _{GS} =10V, I _D =85A		80		nC
Gate-Source Charge	Q _{gs}			32		
Gate-Drain Charge	Q _{gd}			22		
Turn-on delay time	t _{d(on)}	V _{DD} =75V, V _{GS} =10V, I _D =85A, R _G =4.7Ω		26		nS
Turn-on rise time	t _r			36		
Turn-off delay time	t _{d(off)}			47		
Turn-off fall time	t _f			15		
Source-Drain Diode characteristics						
Diode Forward Current ²⁾	I _S				170	A
Diode Forward voltage ³⁾	V _{SD}	V _{GS} =0V, I _S =85A			1.2	V
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F =I _S di/dt = 100A/μs ³⁾		146		nS
Reverse Recovery Charge	Q _{rr}			485		nC

Notes:

- 1) Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2) The value of R_{θJA} is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The value in anygiven application depends on the user's specific board design, and the maximum temperature of 175° C may be used if the PCB allows it.
- 3) Pulse Test: Pulse Width ≤300μs, Duty Cycle ≤2%.
- 4) Guaranteed by design, not subject to production.
- 5) EAS condition : T_J=25°C , V_{DD}=50V, V_G=10V, L=0.5mH, R_G=25Ω.

Typical Characteristics

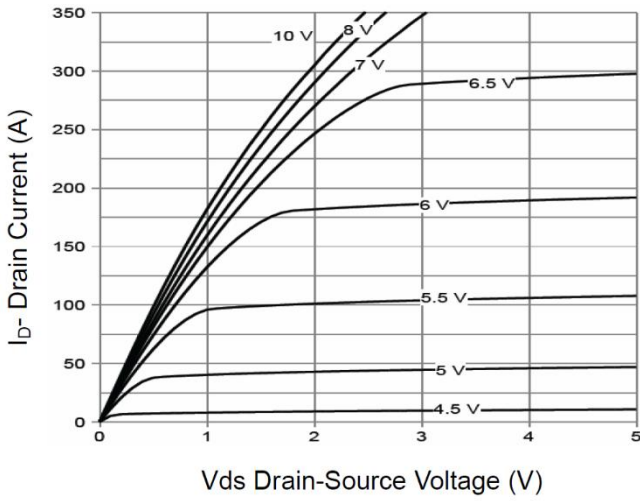


Figure 1 Output Characteristics

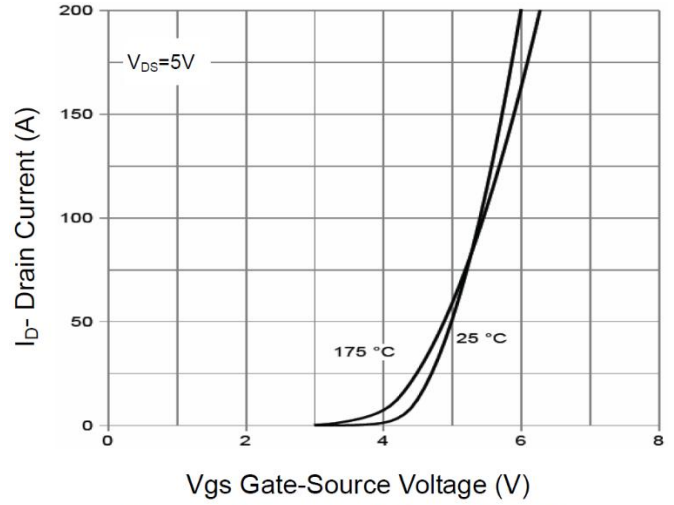


Figure 2 Transfer Characteristics

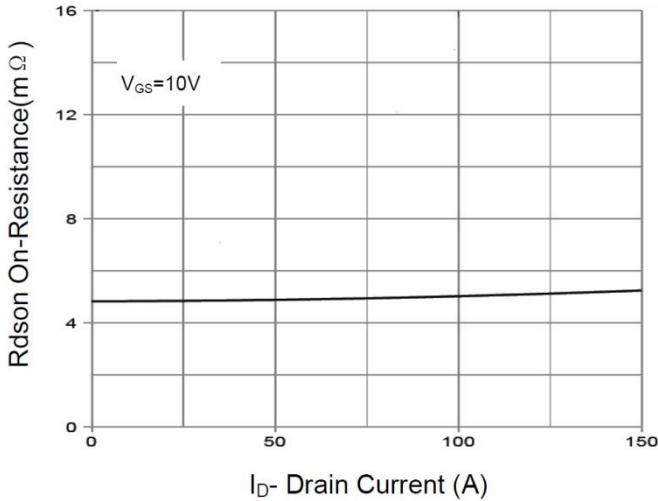


Figure 3 Rdson- Drain Current

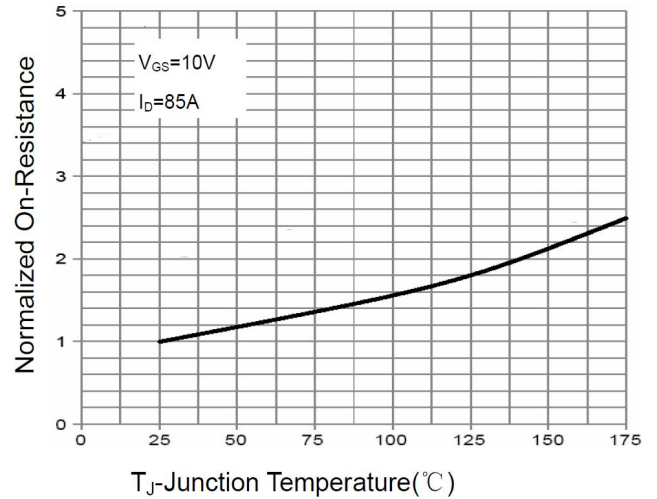


Figure 4 Rdson-Junction Temperature

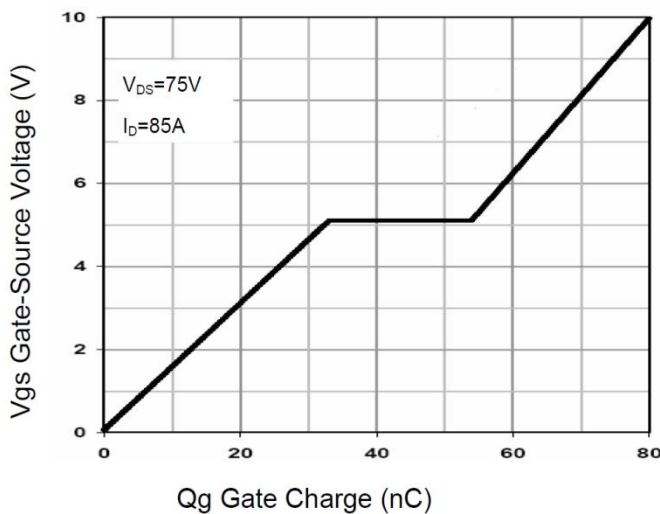


Figure 5 Gate Charge

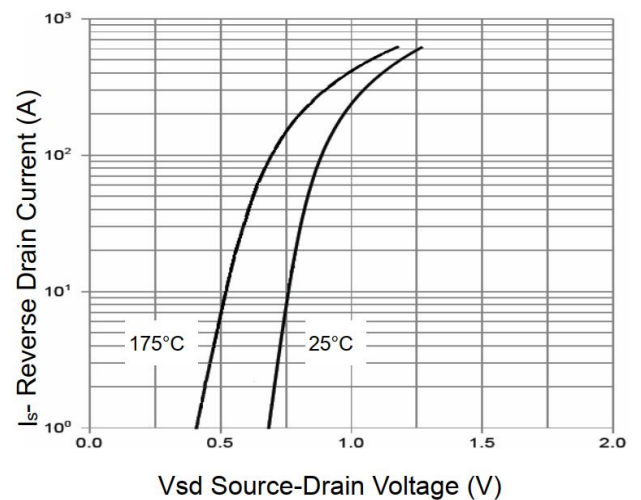


Figure 6 Source- Drain Diode Forward

Typical Characteristics

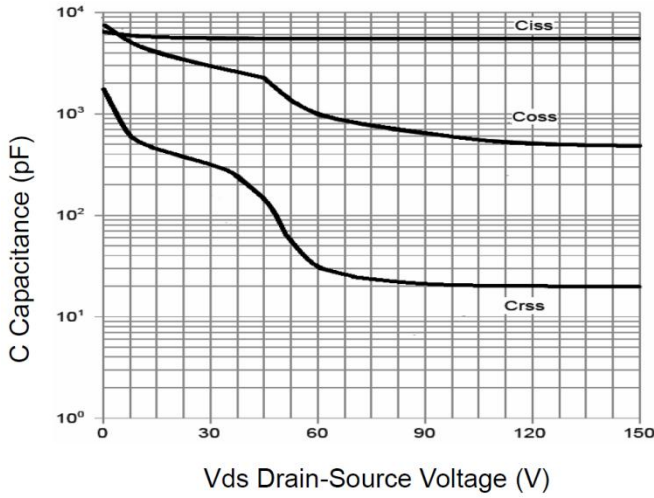


Figure 7 Capacitance vs Vds

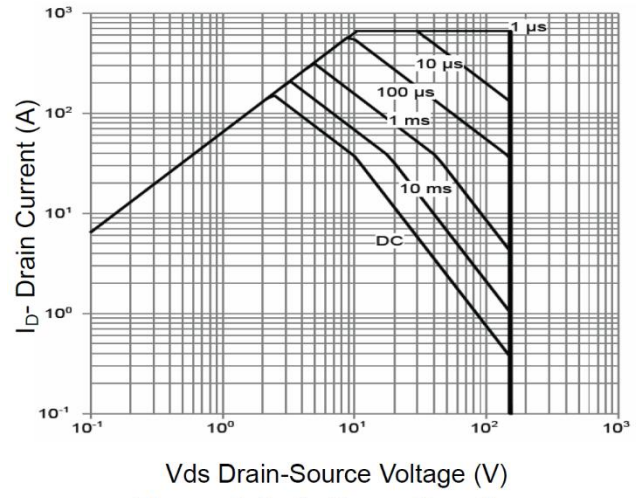


Figure 8 Safe Operation Area

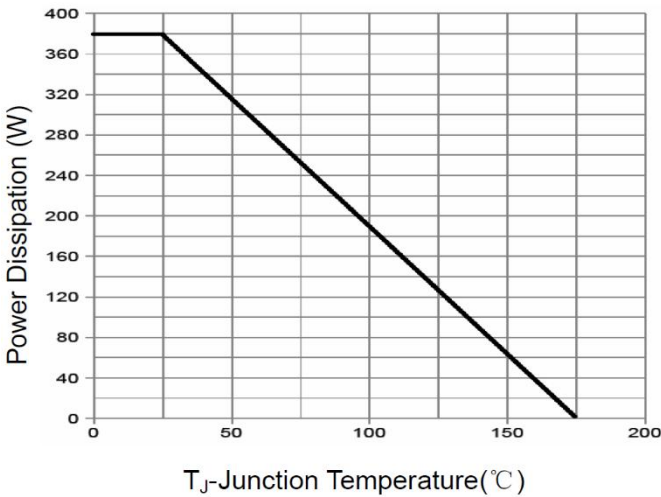


Figure 9 Power De-rating

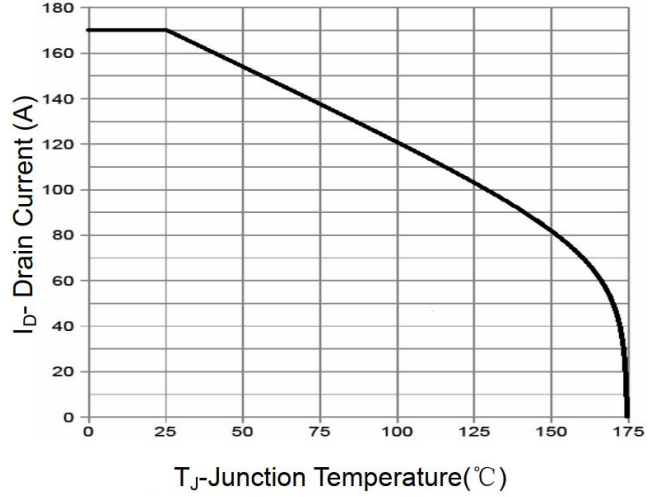


Figure 10 Current De-rating

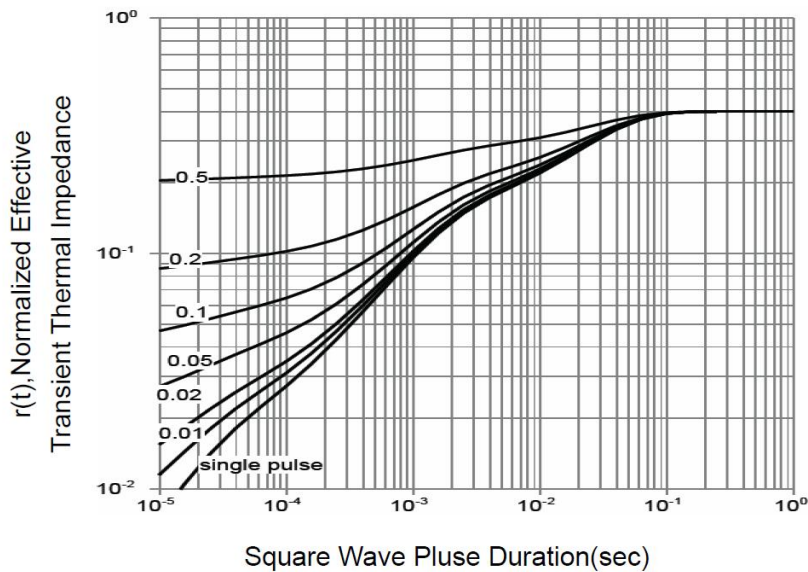
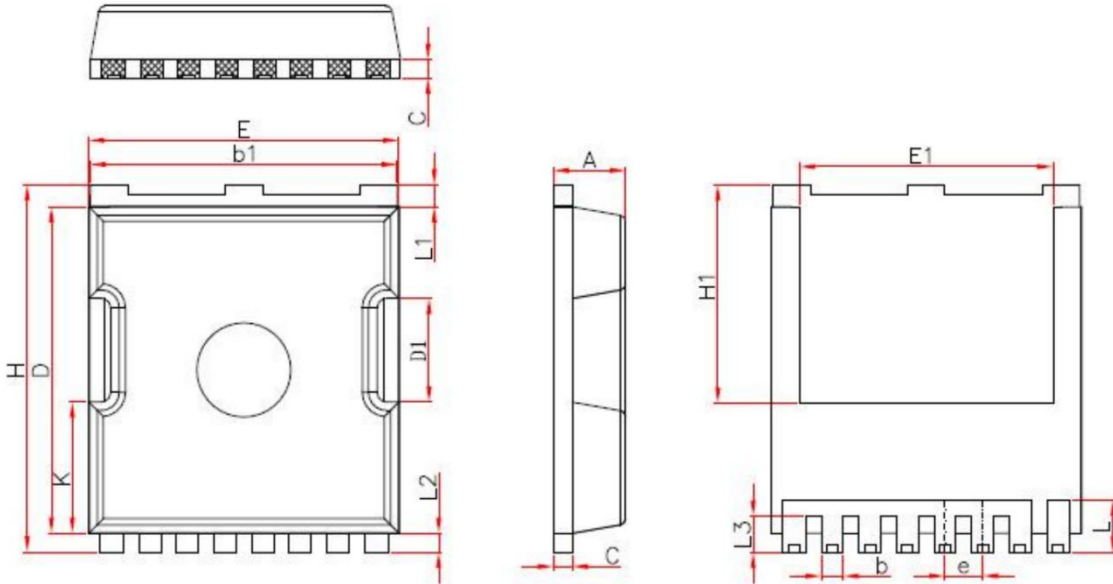


Figure 11 Normalized Maximum Transient Thermal Impedance

TOLL Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
b	0.650	0.850	0.026	0.033
b1	9.700	9.900	0.382	0.390
C	0.500	0.700	0.020	0.027
D	10.300	10.500	0.406	0.413
D1	3.150	3.450	0.124	0.136
E	9.700	10.100	0.382	0.398
E1	8.000	8.200	0.315	0.323
e	1.100	1.300	0.043	0.051
H	11.600	11.800	0.457	0.465
H1	6.850	7.050	0.270	0.278
K	4.080	4.280	0.161	0.169
L	1.600	2.100	0.063	0.083
L1	0.600	0.800	0.024	0.031
L2	0.500	0.700	0.020	0.028
L3	1.050	1.300	0.041	0.051